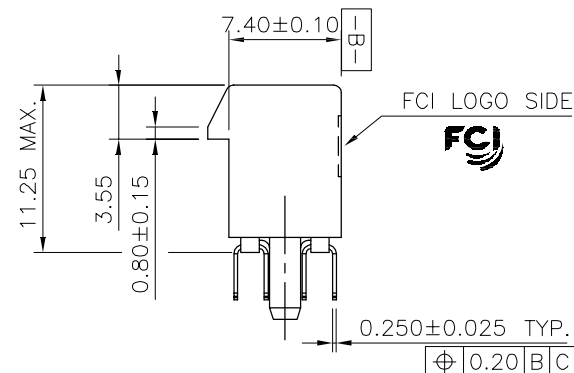
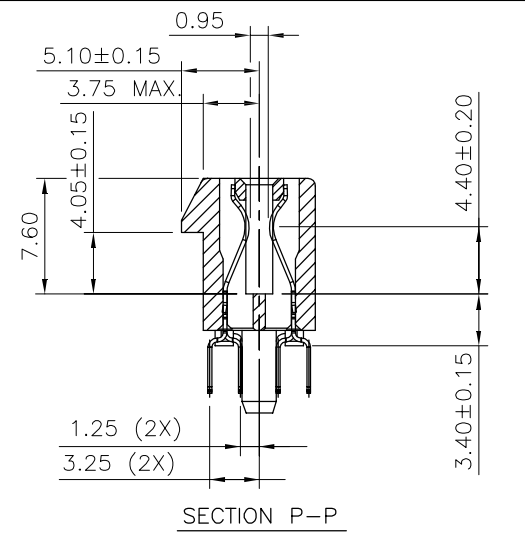
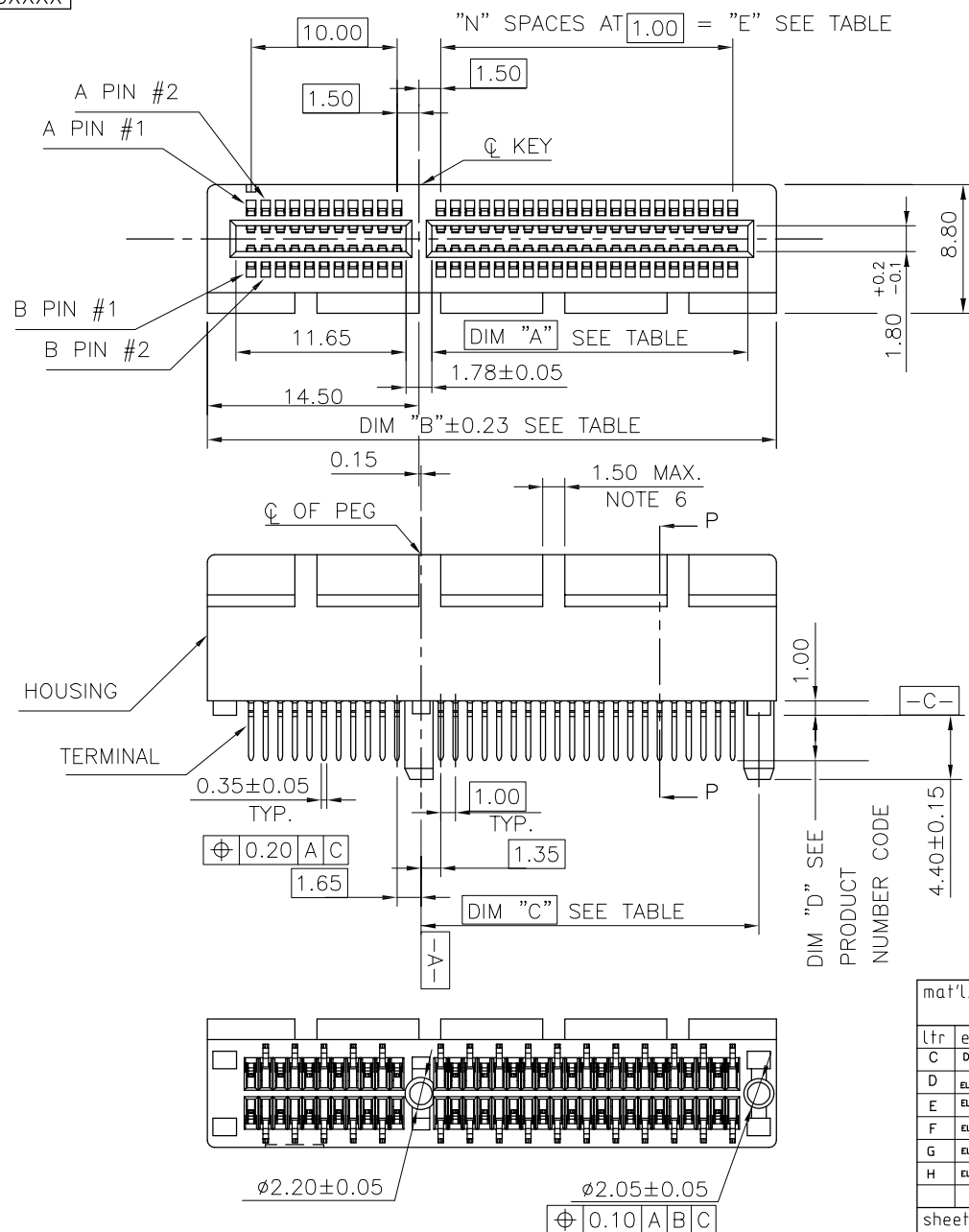
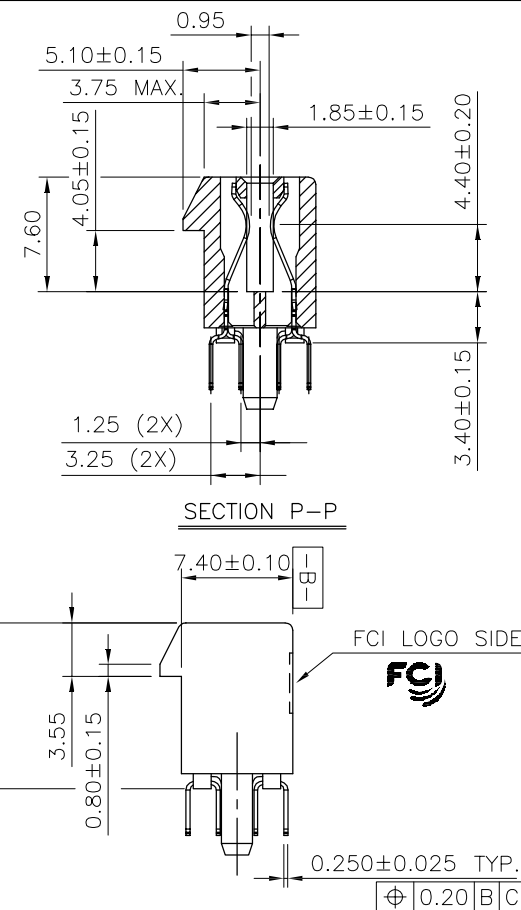
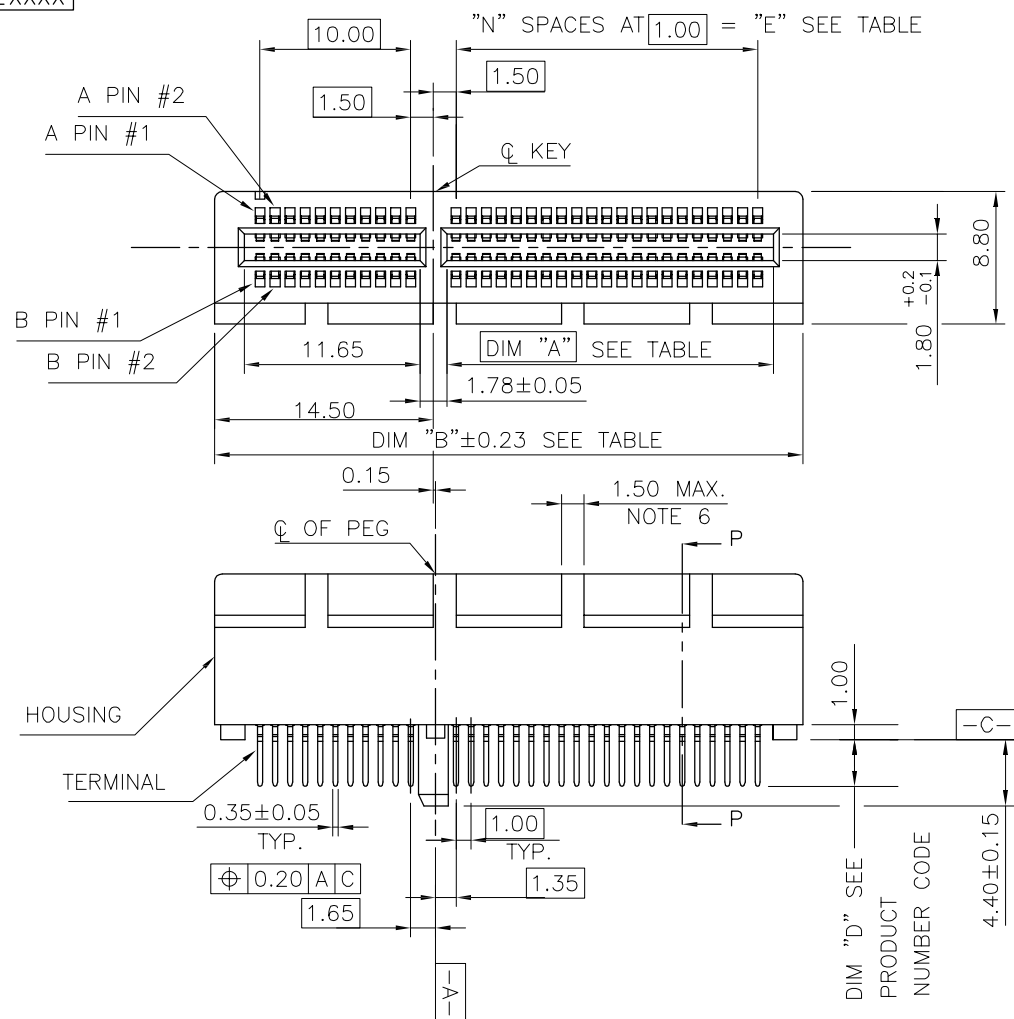


PRODUCT NO.
10108777-X0XXXX

TWIN PLASTIC PEG TYPE

mat'l. code				surface	tolerance	projection	product family	
-				ASME_Y14.5			PCI_EXPRESS	
ltr	ecn no	dr	date	tolerances unless otherwise specified		MM	title	
C	DG-011582	HT	5/10/12	angles	.0±0.30		PCI_EXPRESS_CARD_EDGE_GEN3	
D	ELX-DG-013209	WL	07/24/12	line	.00±0.20	scale N/A	TH_ASS'Y	
E	ELX-DG-2181-1	ST	05/27/15	±2'	.000±0.10		dwg no	
F	ELX-DG-24164	ZH	05/30/16	dr	ZHENHUA_LIU	2016-03-30	sheet 1 of 7	
G	ELX-DG-25671	ZH	12/18/16	engr	ZHENHUA_LIU	2016-03-30	size	
H	ELX-DG-27937	ZH	09/12/17	chr	STONE_LI	2016-03-30	10108777	
		appd	PM_ZHENG	2016-03-30			type	
sheet index		revision	H				CUSTOMER Drawing	

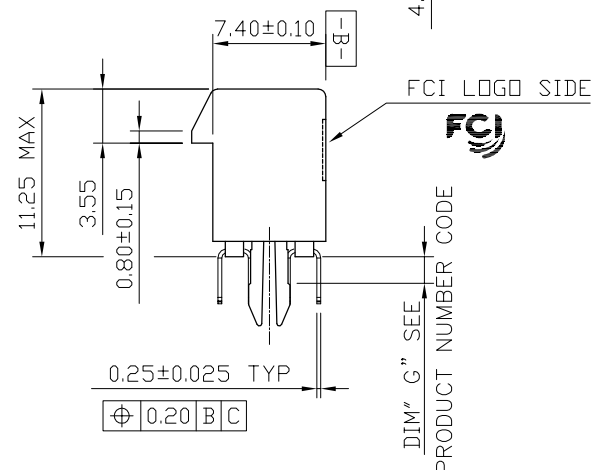
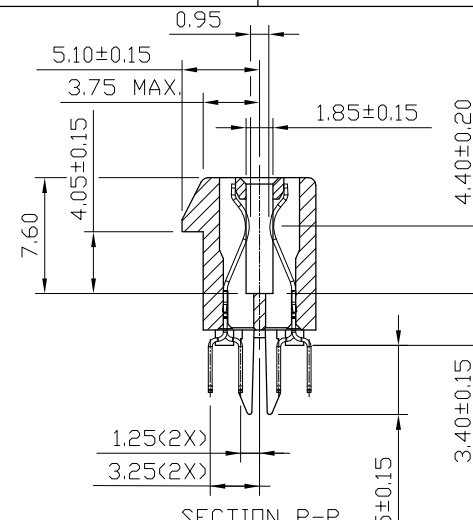
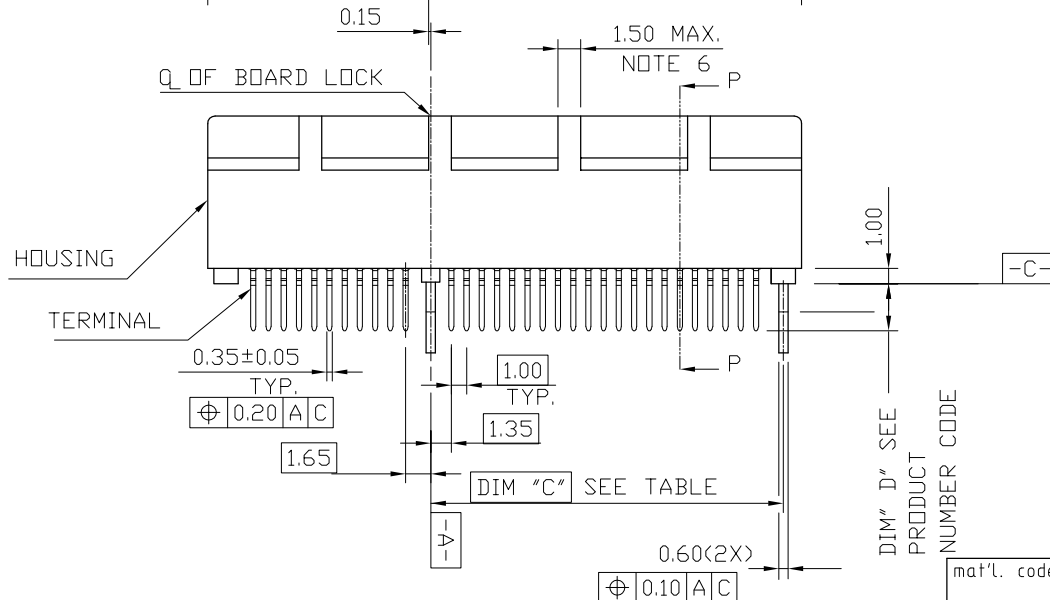
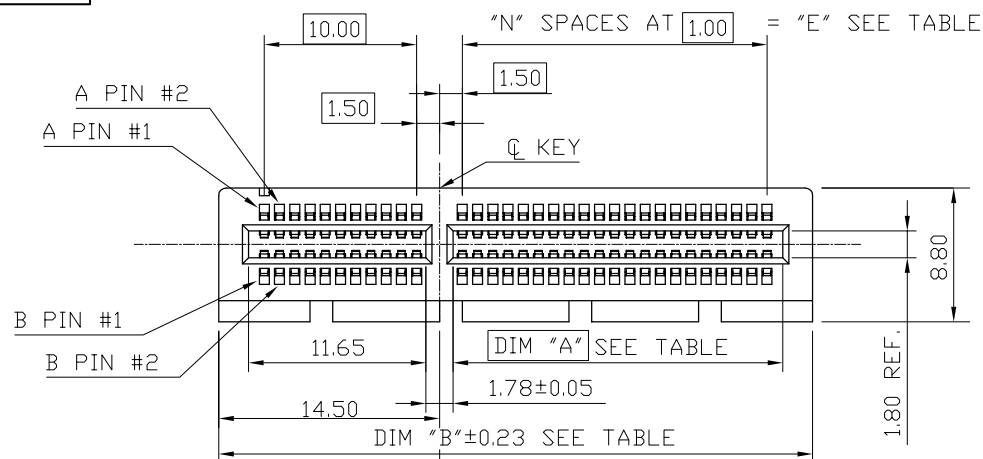
PRODUCT NO.
10108777-X2XXXX



SINGLE PLASTIC PEG TYPE

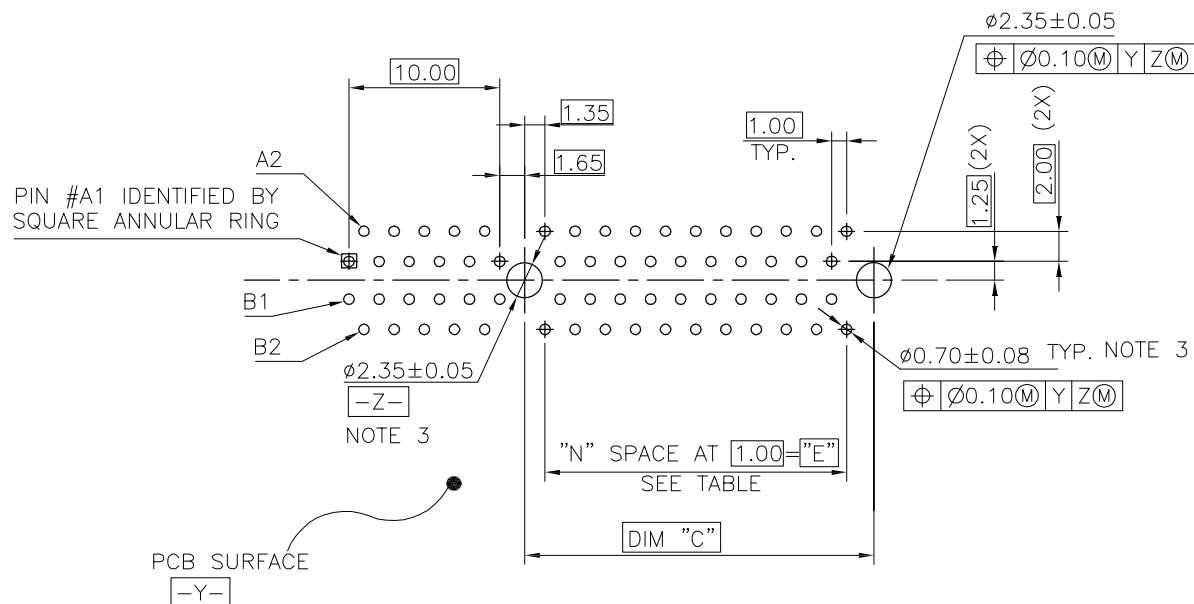
[illegible]

PRODUCT NO.
10108777-X1XXXX



METAL BOARD LOCKS

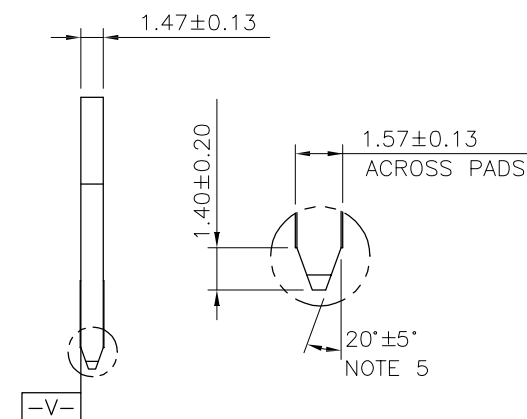
mat'l. code	surface	tolerance	projection	product family
-	ASME_Y14.5	ASME_Y14.5	MM	PCI_EXPRESS
lfr	ecn no	dr	date	title
				PCI_EXPRESS_CARD_EDGE_GEN3
				TH_ASS'Y
				dwg no
				10108777
				type
				CUSTOMER Drawing
sheet	revision	H		
index	sheet			



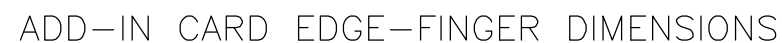
I/O PANEL DIRECTION

RECOMMENDED FOOTPRINT

mat'l. code				surface	tolerance	projection	product family			
-				ASME_Y14.5	ASME_Y14.5		PCI_EXPRESS			
ltr	ecn no	dr	date	tolerances unless otherwise specified			title			
				angles	.0±.0.20	MM	PCI_EXPRESS_CARD_EDGE_GEN3			
				±2'	.00±.0.13	scale N/A	TH_ASS'Y			
				dr	ZHENHUA_LIU 2016-03-30		dwg no		sheet 4 of 7	size
				enr	ZHENHUA_LIU 2016-03-30		10108777		A4	
				chr	STONE_LI 2016-03-30		type		CUSTOMER Drawing	
				appd	PM_ZHENG 2016-03-30					
sheet index	revision sheet	H								



 I/O PANEL DIRECTION
 PRIMARY (COMPONENT) SIDE



# POS REF.	N	DIM "G"	"F"
36	6	8.15	B17
64	20	22.15	B31
98	37	39.15	B48
164	70	72.15	B81

mat'l. code —					surface —		tolerance ASME_Y14.5		projection 		product family PCI_EXPRESS											
ltr ecn no dr date					tolerances unless otherwise specified							title										
					angles		linear		.0±.0.20		MM 		PCI_EXPRESS_CARD_EDGE_GEN3									
									.00±.0.13													
					±2°				.000±.0.05		scale N/A		TH_ASS'Y									
					dr		ZHENHUA_LIU		2016-03-30				dwg no				sheet 5 of 7				size	
					engr		ZHENHUA_LIU		2016-03-30				10108777				A4					
					chr		STONE_LI		2016-03-30													
					appd		PM_ZHENG		2016-03-30													
sheet index		revision sheet		H																		

NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE NYLON, GLASS FILLED UL94V-0 RATED.
TERMINAL: COPPER ALLOY.

PLATING: 50u" NICKEL UNDERPLATE ALL OVER
CONTACT AREA PLATING - SEE PRODUCT NUMBER CODE
SOLDER TAIL: TIN OR TIN /LEAD(90/10)- SEE PRODUCT
NUMBER CODE 100u" MIN. OVER 50u" NICKEL.

METAL BOARD LOCKS: COPPER ALLOY.
FINISH: 100u" TIN OR TIN/LEAD(90/10) OVER 50u" NICKEL
UNDERPLATE SEE PRODUCT NUMBER CODE.

2.PRODUCT SPECIFICATION: GS-12-233.

③THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY

A LINE THROUGH THE CENTER OF THE TWO Ø2.35 HOLES.

THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER
OF DATUM Z.

④NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND PIN NUMBERS "F".

⑤CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

⑥FREQUENCY & LOCATION AT SUPPLIER DISCRETION. RIDGE MAY BE CONTINUOUS WITH NO BREAKS.

7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS:

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um
MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY:

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C TEMPERATURE FOR
10 SECONDS IN RE-FLOW APPLICATION, SEE NOTE 8 FOR APPLICATION.

PRODUCT NUMBER CODE

10108777 -X X X X X X X X

HOUSING COLOR OPTIONS

0-NATURAL
1-BLACK

PEGS OPTIONS

0-PLASTIC PEGS, DIM
1-METAL BOARD LOCKS
2-SINGLE PLASTIC PEGS

TERMINAL PLATING OPTIONS

0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
2-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
3-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ---INCOMPLIANT RoHS
4-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ---INCOMPLIANT RoHS
5-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN/LEAD TAIL AREA ---INCOMPLIANT RoHS

LEAD FREE OPTION

LEAVE BLANK FOR TERMINAL PLATING 3.4.5
"LF" FOR TERMINAL PLATING OPTION 0,1,2

POS OPTIONS

0-36
1-64
2-98
3-164

TAIL LENGTH OPTIONS

	DIM "D"	PCB THICKNESS	DIM "G"
0	2.30 ± 0.25 -0.13	1.56±0.10	1.70±0.15
1	3.10 ± 0.25 -0.13	2.36±0.10	2.50±0.15
2	2.54±0.25	1.56±0.10	1.70±0.15
3	1.90±0.25	1.56±0.10	1.70±0.15
4	3.10 ± 0.25 -0.13	2.0±0.10	1.70±0.15

CONNECTOR	# POS REF.	N	DIM "A"	DIM "B"	DIM "C"	"E"
1 PORT	36	6	7.65	25.00	9.15	6.00
4 PORT	64	20	21.65	39.00	23.15	20.00
8 PORT	98	37	38.65	56.00	40.15	37.00
16 PORT	164	70	71.65	89.00	73.15	70.00

8.AN ADEQUATE PROCEDURE SET FORTH IN THE FOLLOWING ENSURE THAT THE PRODUCT
RELIABILITY CAN BE ACHIEVED DURING AND AFTER PCB ASSEMBLY OPERATION.

8.1IF PARTIAL LOT ARE USED, THE REMAINING CONNECTORS MUST BE RESEALED AND
PLACED IN SAFE STORAGE WITHIN SIX HOURS OF BAG OPENING.

8.2THE SAFE STORAGE CONDITION IS RECOMMENDED AT 25°C, 40%RH.

8.3NOT FOLLOWING THE PROCEDURE MAY CAUSE BLISTER DAMAGE DURING RE-FLOW PROCESS.

8.4IF BAKING IS REQUIRED, CONNECTOR SHALL BE BAKED FOR 4 HOURS AT 125°C.

8.5REFERENCE SPECIFICATION: IPC/JEDEC J-STD-033A.

PACKAGING OPTIONS

E-HARD TRAY WITH MYLAR FOR VACUUM PACKAGING (FOR 164P ONLY)

T-SOFT TRAY PACKAGING

C-SOFT TRAY PACKAGING WITH 10MM CAP

M-SOFT TRAY PACKAGING & MYLAR TAPE. SEE FIGURE 1

Y-HARD TRAY PACKAGING (FOR 36P,98P AND 164P ONLY)

Z-HARD TRAY PACKAGING WITH MYLAR (FOR 36P,98P AND 164P ONLY)

H-SMALLER HARD TRAY PACKAGING WITH 30MM CAP (323X136X17.7 FOR 164P ONLY)

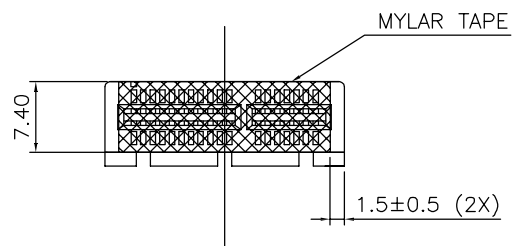
Q-SMALLER HARD TRAY PACKAGING (323X136X17.7 FOR 164P ONLY)

R-TAPE & REEL PACKAGING WITHOUT MYLAR
(FOR 34, 64, 98P ONLY)

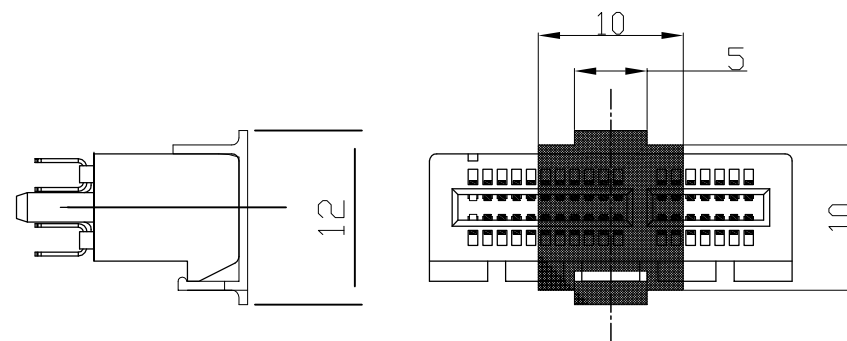
W-TAPE & REEL PACKAGING WITHOUT MYLAR
(FOR 98P ONLY), WITH 18.0MM CAVITY WIDTH

A-TAPE & REEL PACKAGING WITH MYLAR
(FOR 36, 64, 98P ONLY)

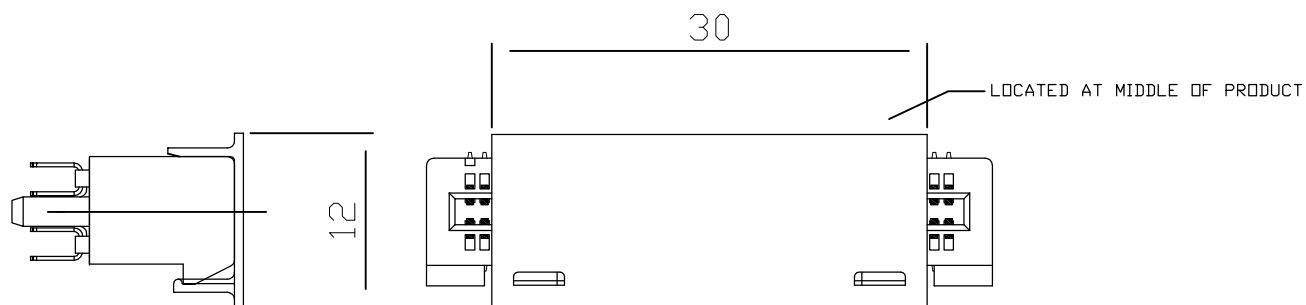
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lfr	ecn no	dr	date	tolerances unless otherwise specified			title
				angles	.0±0.30		PCI_EXPRESS_CARD_EDGE_GEN3
				lineal	.00±0.20		TH_ASS'Y
				±2'	.000±0.10	scale N/A	
		dr	ZHENHUA_LIU	2016-03-30			
		engr	ZHENHUA_LIU	2016-03-30			
		chr	STONE_LI	2016-03-30			
		appd	PM_ZHENG	2016-03-30			
sheet	revision	H					dwg no
index	sheet						10108777
							type
							CUSTOMER Drawing



POSTION OF MYLAR



POSTION OF CAP (10×10)



POSTION OF 30MM CAP(30X12)

mat'l. code				surface	tolerance	projection	product family		
-				-	ASME_Y14.5		PCI_EXPRESS		
ltr	ecn no	dr	date	tolerances unless otherwise specified			title		
				angles	.0±0.30	MM	PCI_EXPRESS_CARD_EDGE_GEN3		
				linear	.00±0.20		TH_ASS'Y		
				±2'	.000±0.10	scale N/A			
				dr	ZHENHUA_LIU	2016-03-30	dwg no		sheet 7 of 7
				enr	ZHENHUA_LIU	2016-03-30	10108777		size
				chr	STONE_LI	2016-03-30			A4
				app	PM_ZHENG	2016-03-30	type		CUSTOMER Drawing
sheet	revision	H							
index	sheet								



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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Факс: 8 (812) 320-02-42

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